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NOTICE OF LISTING ON THE STOCK EXCHANGE OF HONG KONG LIMITED



SHENWAN HONGYUAN (H.K.) LIMITED

申萬宏源（香港）有限公司

(Incorporated in Hong Kong with limited liability)

(Stock code: 218)

U.S.\$200,000,000 1.5 PER CENT. BONDS DUE 2023 (the “BONDS”)

(Stock Code: 4453)

Issue Price: 100.0 per cent.

Joint Global Coordinators, Joint Lead Managers and Joint Bookrunners

Shenwan Hongyuan (H.K.)	CMB Wing Lung Bank Limited	Industrial Bank Co., Ltd. Hong Kong Branch	Shanghai Pudong Development Bank Hong Kong Branch	China Industrial Securities International	China Construction Bank (Asia)
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Joint Lead Managers and Joint Bookrunners

China International Capital Corporation	China Merchants Securities (HK)	CCB International	CMB International	CEB International	Central China International	China Galaxy International Securities (Hong Kong) Co., Ltd.
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Application has been made to The Stock Exchange of Hong Kong Limited for the listing of and permission to deal in the Bonds as described in the offering circular dated 20 January 2022, by way of debt issues to professional investors (as defined in Chapter 37 of the Rules Governing the Listing of Securities on The Stock Exchange of Hong Kong Limited) only. The listing of the Bonds is expected to become effective on 28 January 2022.

By order of the Board
SHENWAN HONGYUAN (H.K.) LIMITED
Liang Jun
Executive Director & Chief Executive Officer

Hong Kong, 27 January 2022

As at the date of this announcement, the board of directors of SHENWAN HONGYUAN (H.K.) LIMITED (申萬宏源(香港)有限公司) comprises eight directors, of which Ms. Wu Meng, Mr. Guo Chun, Mr. Zhang Jian and Mr. Liang Jun are the executive directors; Mr. Zhang Lei is the non-executive director; Mr. Ng Wing Hang Patrick, Mr. Kwok Lam Kwong Larry and Mr. Chen Liqiang are the independent non-executive directors.